

**(57) Abstract:**

The invention relates to a method for constructing EMI shielding around a component embedded in a circuit board. According to the method, a recess, which is extended to an insulating layer that represents the ground-reference plane, is formed around the embedding location of the component. The recess is filled or surfaced with an electrically conductive material, in such a way that the material is in electrical contact with the ground-reference plane and that the material essentially surrounds the component in the direction of the circuit board.